

AMENDMENTS TO THE CLAIMS

1-35. (Canceled)

36. (Previously Presented) A manufacturing method of a packaged electronic device comprising:

bonding a first container member on which an electronic device is mounted and a second container member configured to form a space for housing said electronic device in cooperation with said first container member with a metal layer for closing the space;

when said bonding, radiating an energy wave to a first metal part of said first container member and a second metal part of said second container member while said first metal part and said second metal part are heated at a room temperature or higher and 150°C or lower in atmospheric air; and

forming said metal layer by bringing said first metal part and said second metal part radiated with said energy wave into contact with each other.

37. (Previously Presented) A packaged electronic device comprising:

a container configured to form a closed inner space by a first inner face, a second inner face opposed to said first inner face, and side faces perpendicular to said first inner face and said second inner face;

a first electronic device to be mounted on a first mounting face of said first inner face, said second inner face, or said side faces;

a second electronic device to be mounted on a second mounting face different from said first mounting face of said first inner face, said second inner face, or said side faces;

a first outer electrode formed on an outer face of said container facing to said first mounting face and configured to be electrically connected with said first electronic device; and

a second outer electrode formed on an outer face of said container facing to said second mounting face and configured to be electrically connected with said second electronic device,

said container including a recessed part; a main body member configured to mount said second electronic device on a bottom of said recessed part; a first cover member configured to be attached to an aperture of said recessed part and configured to mount said first electronic device; and a metal layer configured to close said inner space by bonding said main body member and said first cover member,

said metal layer being formed by radiating an energy wave to metal parts of said main body member and said first cover member while said metal parts are heated at a room temperature or higher and 150°C or lower in atmospheric air, and by bringing said radiated and heated metal parts into contact with each other.

38. (Previously Presented) A manufacturing method of a packaged electronic device comprising:

mounting a first electronic device to be connected electrically with a first via on a first mounting face of a cover member having the first via formed therein;

mounting a second electronic device to be connected electrically with a second via on a

second mounting face of a main body member having the second via formed therein and forming a closed inner space in cooperation with said cover member; and

forming a packaged electronic device by bonding said cover member and said main body member so as to arrange said first electronic device and said second electronic device in said inner space and thereby closing said inner space,

said bonding of said cover member and said main body member being carried out by:

radiating an energy wave to a first metal part formed on said first mounting face of said cover member and a second metal part formed on said main body member while said first metal part and said second metal part are heated at a room temperature or higher and 150°C or lower in atmospheric air; and

thereafter, forming said packaged electronic device by bonding said cover member and said main body member with said first metal part and said second metal part connected and closing said inner space.

39. (Previously Presented) The manufacturing method of a packaged electronic device according to claim 38, wherein said electric connection of said first and second vias with said first electronic device and said second electronic device is carried out by radiating an energy wave to said first and second vias, and electrodes of said first electronic device and said second electronic device; and thereafter bringing said first and second vias into contact with said first electronic device and said second electronic device.

40. (Previously Presented) The manufacturing method of a packaged electronic device according to claim 38, wherein said electric connection of said first and second vias with said first electronic device and said second electronic device is carried out by providing a curable anisotropic conductive or non-conductive resin between electrodes of said first electronic device and said second electronic device, and said first and second vias.